TWSE STOCK CODE 1560

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KINIK

3Q25 Investor Conference



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Outline

- Welcome — William Lee, DBU President/Spokesperson; Tony Pai, Vice President/Acting Spokesperson
- Company overview
- 3Q25 financial results
- 2025 outlook
- Q & A
- **Appendix:** KINIK Visions/Missions, Products, Plants information

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Company Overview

- Company established in 1953; Taiwan Stock Code 1560
- Capital : 1,469 Million(TWD) (Sep. 30 2025)
- Employees : ~2400 worldwide. (~1800 in Taiwan.)
- 2024 revenue 7,019M TWD, EPS=7.1
- Main products by 3 BUs & subsidiaries, and Sales Ratio in 2025H1

Product Introduction

ABU: Abrasives BU

Subsidiaries: KTC/Hongia/MKS/MGT

Sales Ratio: 22%



Grinding wheel
(Machinery & Mechanical Indus.)

DBU: Diamond BU

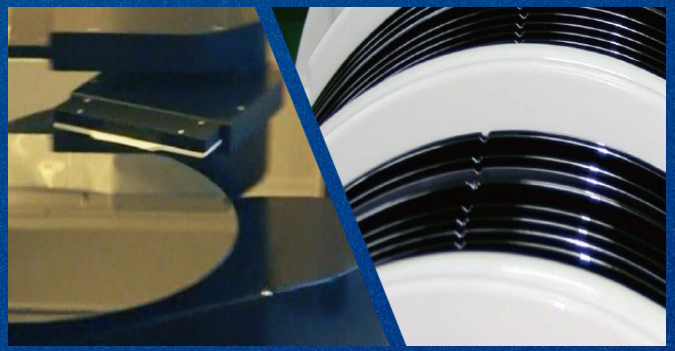
30%



CMP Diamond Disk
(Semiconductor Indus.)

SBU: Semiconductor Material BU

48%



Reclaim & Test Si Wafer
(Semiconductor Indus.)

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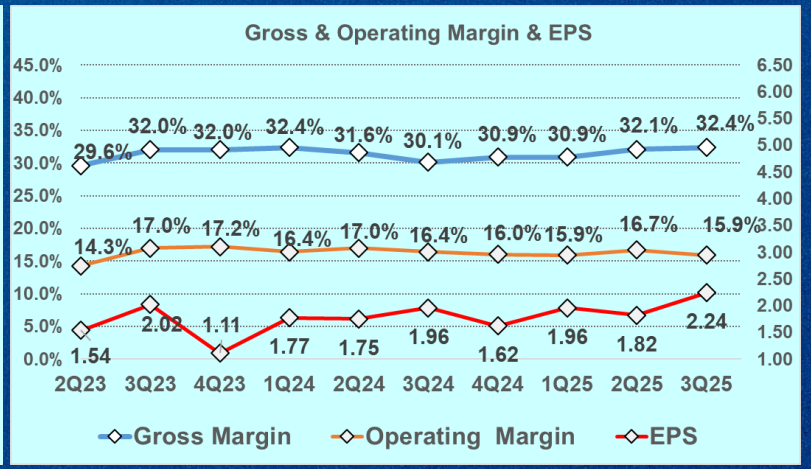
3Q25 Consolidated Income statement

- 3Q25 consolidated revenue: NTD 2.09 billion, QoQ -1.1%; Gross margin: 32.4% (+0.3ppt); EPS=2.24.
- NTD appreciated 3.6% vs. USD in 3Q, impacting gross margin by ~1.6%. However, higher mix of high-end products led to overall gross margin improving QoQ by 0.3%.
- Non-operating gain of NTD 83.7M: Includes FX and valuation gain of NTD 70M.

Accounting Period Income (all in thousands TWD except *)	3Q25	2Q25	QoQ	1Q~3Q25	1Q~3Q24	YoY
*Net Revenue(USD thousand)	70,219	68,421	2.6%	192,480	161,827	18.9%
Net Revenue	2,091,277	2,114,763	-1.1%	5,977,667	5,185,481	15.3%
Gross Margin	32.4%	32.1%	+0.3 ppt	31.9%	31.3%	+0.6 ppt
Operating Expenses	(344,094)	(327,610)	5.0%	(937,829)	(760,738)	23.3%
Operating Margin	15.9%	16.7%	-0.8 ppt	16.2%	16.6%	-0.4 ppt
Non-Operating Items	83,737	(15,958)	99,695	101,573	120,362	(18,789)
Net Income to Shareholders of the Parent Company	328,438	266,366	23.3%	880,619	795,708	10.7%
Net Profit Margin	15.8%	13.3%	+2.5 ppt	15.1%	15.7%	-0.6 ppt
EPS	2.24	1.82	23.1%	6.02	5.48	9.9%
ROE	17.3%	15.1%	+2.2 ppt	15.7%	15.9%	-0.2 ppt
Average Exchange Rate-USD/NTD	29.78	30.91	-3.6%	31.12	32.05	-2.9%



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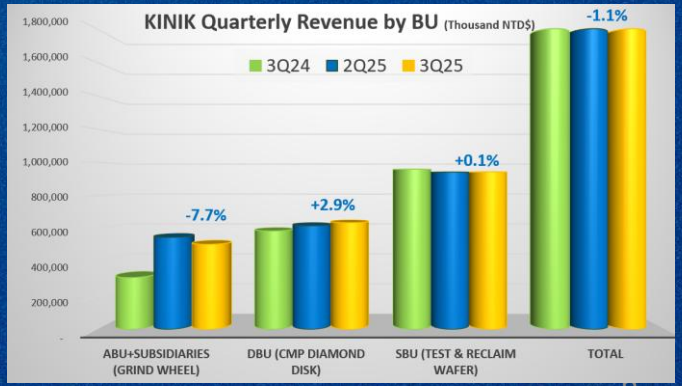
3Q25 Sales Performance by BUs

ABU: Grinding Wheel **DBU: CMP Pad Conditioner** **SBU: Reclaim/Test Wafer**
Subsidiaries: Hongia, KTC, MKS, MGT

- Company-wide: 3Q25 revenue of NTD 2.09 billion, QoQ -1.1%, YoY +12.5%.
- Grinding Wheel: Revenue declined 7.7% QoQ, impacted by weak demand in the machinery and mechanical industries.
- CMP Diamond disk: shipments for advanced nodes and advanced packaging increased, driving QoQ revenue growth of 2.9%.
- Wafer: 12-inch monthly capacity rose 10% to 330K from July. Q3 saw higher shipments of high-end reclaim wafers, offset by lower special wafer sales. Revenue up 0.1% QoQ.

Business Unit	3Q24	2Q25	3Q25		QoQ	YoY
ABU+subsidiaries (Grind Wheel)	310,326	551,671	509,168	24%	-7.7%	64.1%
DBU (CMP Diamond Disk)	589,715	620,784	638,589	31%	2.9%	8.3%
SBU (Test & Reclaim Wafer)	959,557	942,307	943,521	45%	0.1%	-1.7%
Total	1,859,597	2,114,763	2,091,277	100%	-1.1%	12.5%



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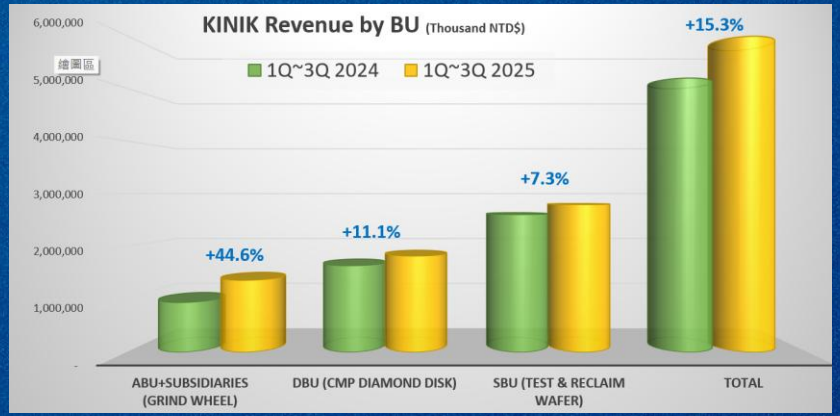
1~3Q25 Sales Performance by BUs

ABU: Grinding Wheel **DBU:** CMP Pad Conditioner **SBU:** Reclaim/Test Wafer
Subsidiaries: Hongia, KTC, MKS, MGT

- **Company-wide:** Company-wide: 1Q~3Q25 revenue up 15.3% Y0Y.

Business Unit	1Q~3Q 2024	1Q~3Q 2025		YoY
ABU+subsidiaries (Grind Wheel)	941,712	1,362,162	23%	44.6%
DBU (CMP Diamond Disk)	1,638,601	1,820,791	30%	11.1%
SBU (Test & Reclaim Wafer)	2,605,169	2,794,715	47%	7.3%
Total	5,185,481	5,977,667	100%	15.3%



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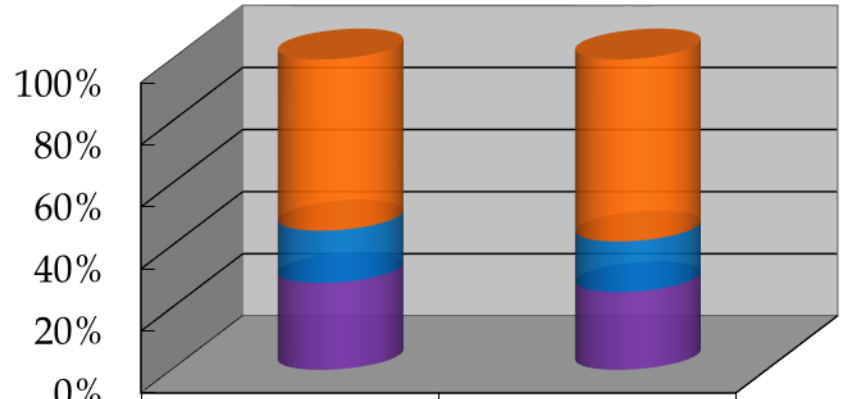
3Q25 Diamond Disk Sales (1/2)

Diamond Disk Sales Ratio by Region



	2025 Q2	2025 Q3
Taiwan / Unique One	55.18%	58.65%
Taiwan / Others	16.85%	16.32%
Oversea customers	27.97%	25.03%

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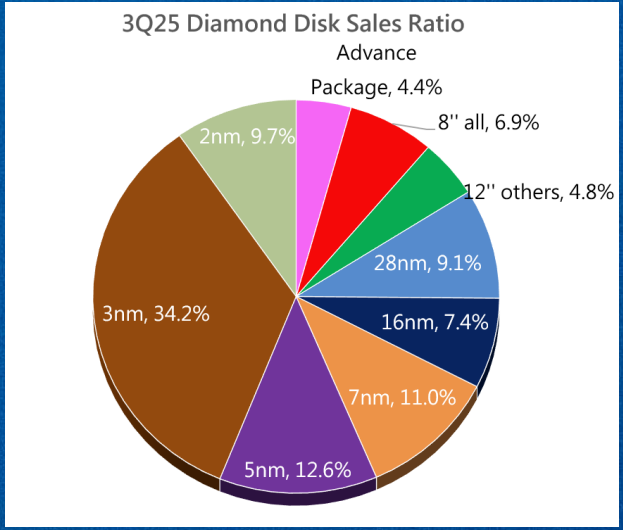
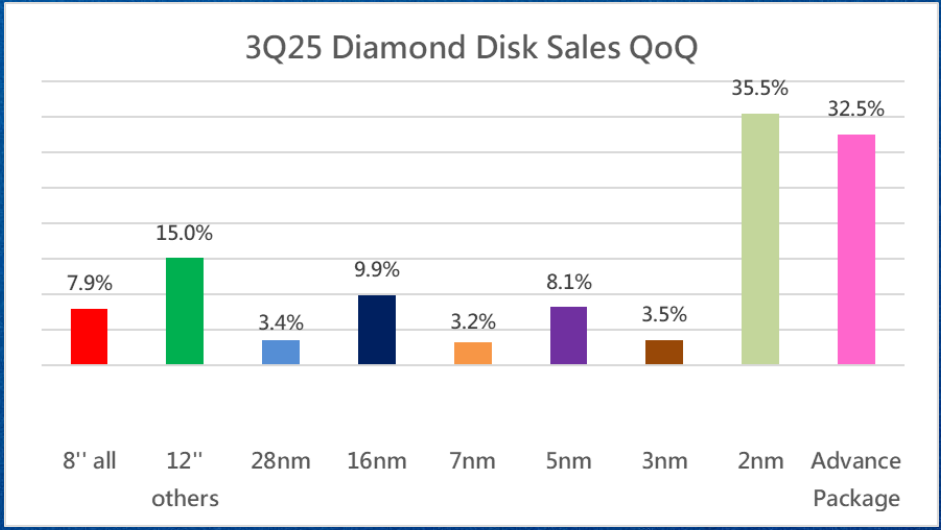
3Q25 Diamond Disk Sales (2/2)

- 3Q25 DBU revenue: NTD 639M, QoQ +2.9%.
- Revenue ratio from the one specific customer's advanced technologies (sub-5nm) products and advanced packaging rose from 60% to 61%; 2nm diamond disk shipments surged 35.5%.





Remark：Data regards to one specific customer.

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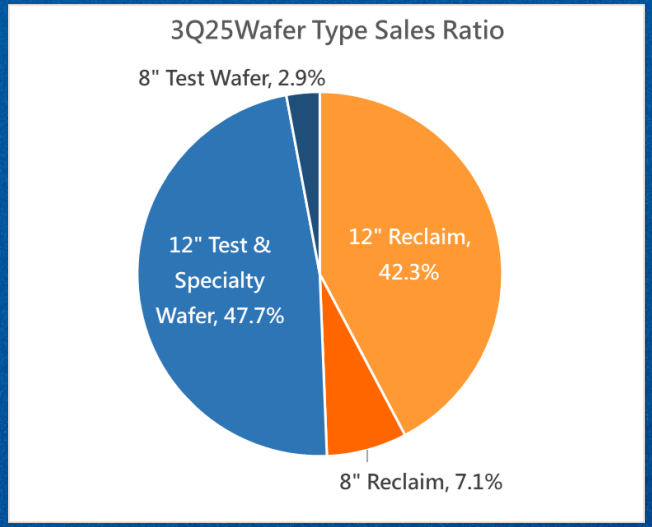
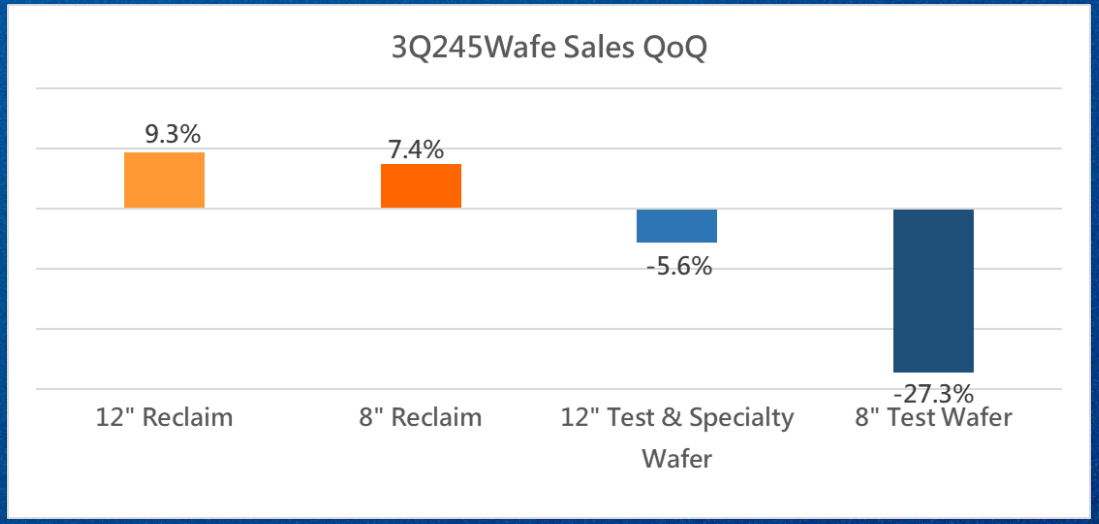
3Q25 SBU Wafer Sales

- 3Q25 SBU revenue reached NTD 943M, up 0.1% QoQ.
- Sales from high-end reclaim wafers increased, while test and specialty wafers declined QoQ.





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Summary of Recent Key Events

- In accordance with the 2020 and 2022 employee stock option plans, a total of 407,500 shares were exercised between July 1 and September 30, 2025 (Year 114), raising NT$59.39 million. After capital increase, the paid-in capital reached NT$1,469.41 million. The record date for this capital increase is set on October 28, 2025.

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2025 Outlook

- ABU Grinding Wheel Business Unit and Subsidiaries
  - H2 2025: Taiwan traditional machinery/tool customers affected by FX and tariffs, lowering utilization.
  - Revenue from newly acquired Japan MKS and Thailand MGT expected to remain flat.
- DBU CMP Diamond Disk
  - Demand for diamond disks used in advanced and 2nm processes continues to increase in Q4.
  - A newly added overseas IDM customer began contributing revenue from Q3 through successful adoption in its most advanced nodes. From Q4 onward, sampling for its mature processes is underway, with volume expected to ramp up each quarter.
  - Total monthly shipments expected to reach nearly 50,000 units by year-end; capacity expansion will continue in 2026..
- SBU Reclaim/Test/Specialty Wafer:
  - Current 12-inch capacity remains fully utilized at 330K wafers per month. Starting in Q3 2026, capacity will expand by 70K to reach 400K wafers per month to meet growing demand from advanced process customers.
  - The proportion of high-end product mix is expected to continue rising in Q4, helping to mitigate exchange rate impact and improve gross margin.

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Q & A

Thanks for your attention

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Appendix

- Company Philosophy, Mission, and Vision
- Introduction of KINIK Products
- Plants Information
- Company Milestone

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KINIK Company

經營理念 Business philosophy

共好 Good together

你好，我好，大家好 Good to You, Me, All

使命 Mission

Keep creating innovative values for industries and customers.

精益求精為產業與客户創新價值

願景 Vision

成為研磨解決方案的卓越智造與服務中心

Become an excellent and intelligent smart manufacturing and service center for grinding solutions.

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History, Now, and Future of KINIK



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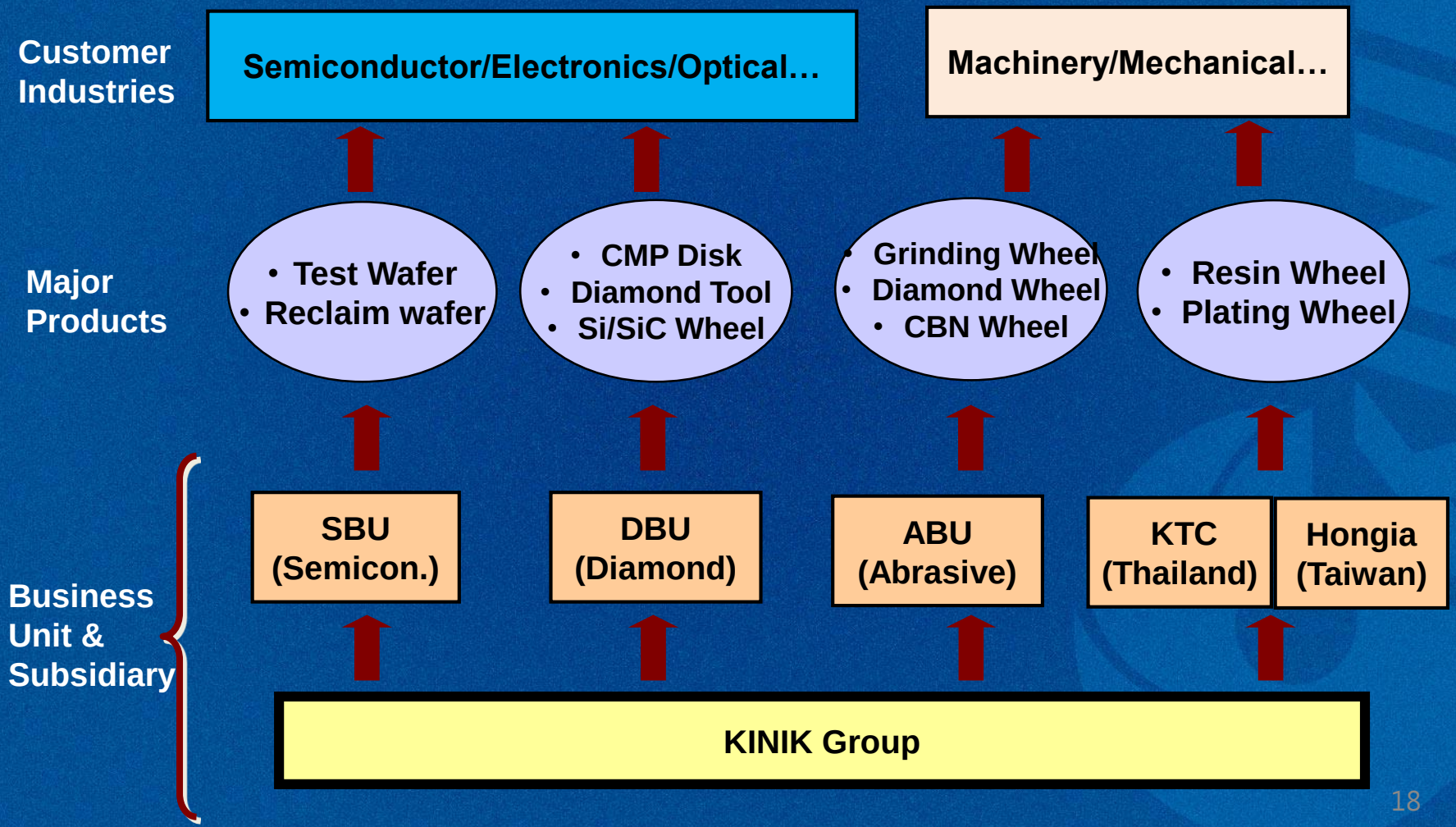
Core Technology “ Grinding”



Major Product and Business Diagram



KINIK COMPANY

中砂公司 TWSE STOCK CODE 1560



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KINIK

中砂產品介紹

Products Introduction

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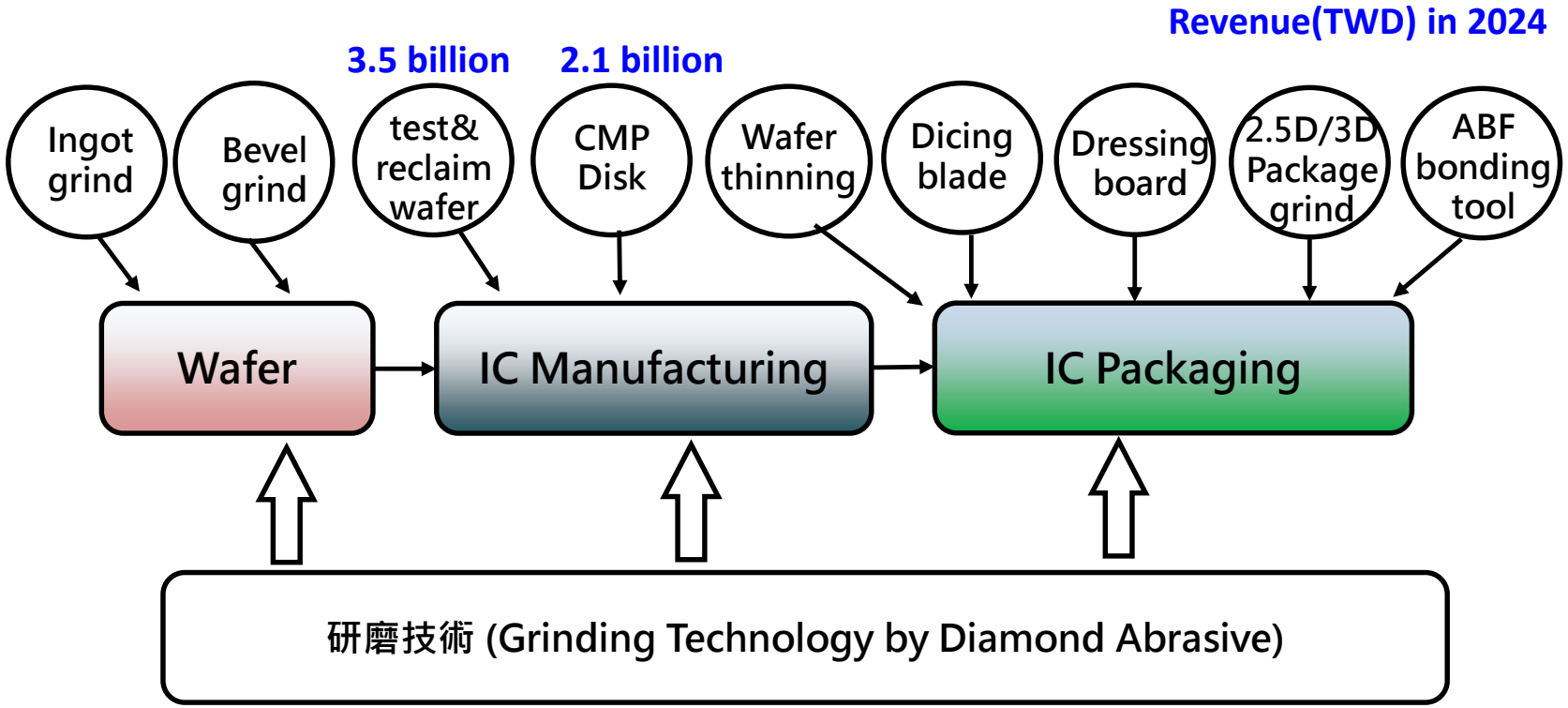
KINIK's products in Semiconductor Industries



In 2024, revenue from semiconductor industries was 5.8 billion (82% of total)
The gross margin is 34%(3% higher than the total average (30.4%))

測試&再生晶圓 Test/Reclaim Wafer

What is test and reclaim wafer?

The source of the reclaimed wafers comes from the monitor wafers and the dummy wafers but not the defect wafers manufactured by the semiconductor fab. The services we provide to refurbish these reclaimed wafers can dramatically lower the running cost of a semiconductor manufacturer.

The reclaimed wafers can be categorized according to functions as figure 1 and the reclamation system is shown as figure 2.

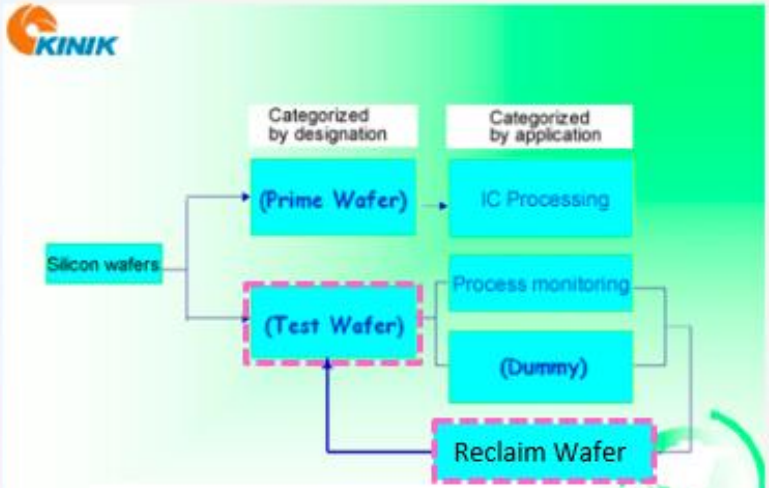


Figure 1 - The classification of the wafer application

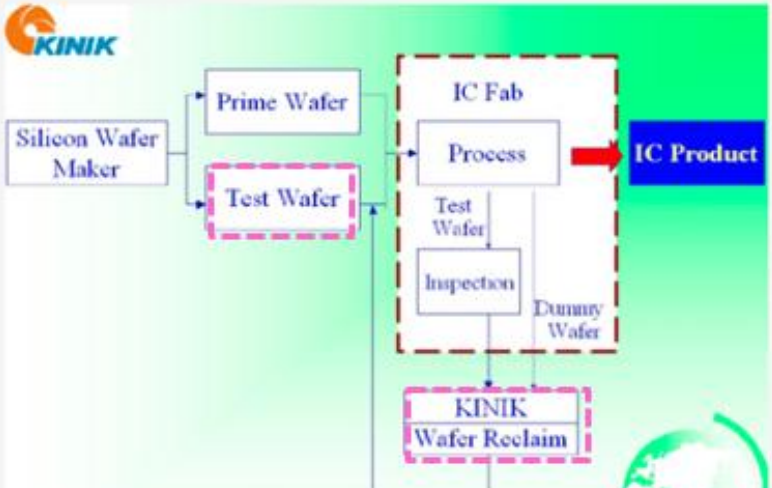


Figure 2 -The reclamation system for the reclaimed wafer

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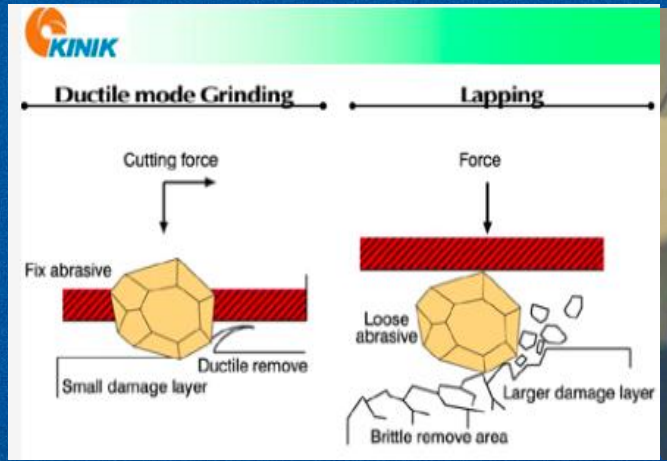
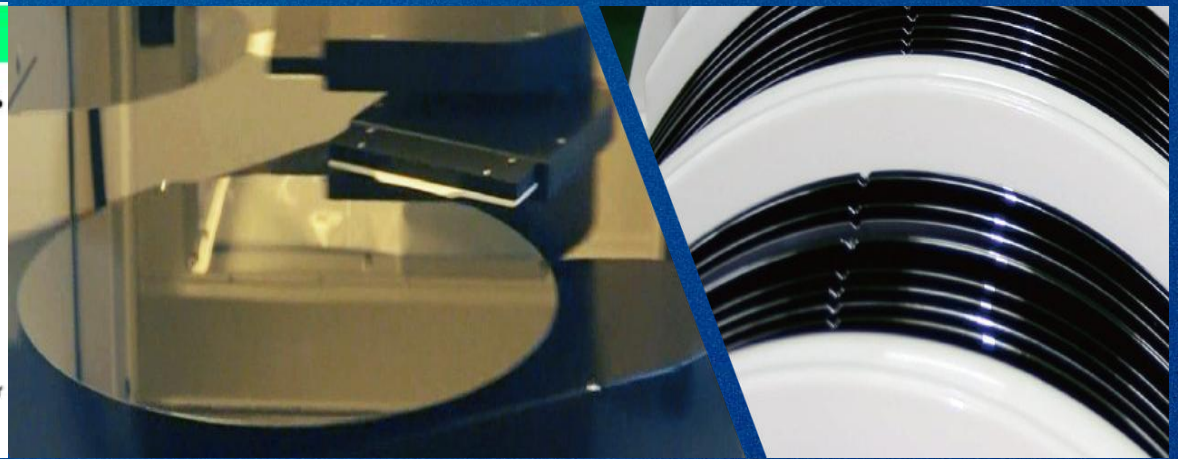
測試&再生晶圓 Test/Reclaim Wafer

中砂的再生晶圓之製程特色以延性輪磨(Ductile Mode Grinding)加工取代傳統研磨(Lapping)加工，目的是降低加工之變質層，減少化學藥品污染，且可提高加工精度，為最先進之再生晶圓製程。

The features of the KINIK reclaimed wafers are refurbished by ductile mode grinding used to replace traditional lapping to lower the strained thickness on the surface and chemical contamination. The ductile mode grinding is the leading-edge process for the high precious reclaimed wafers.





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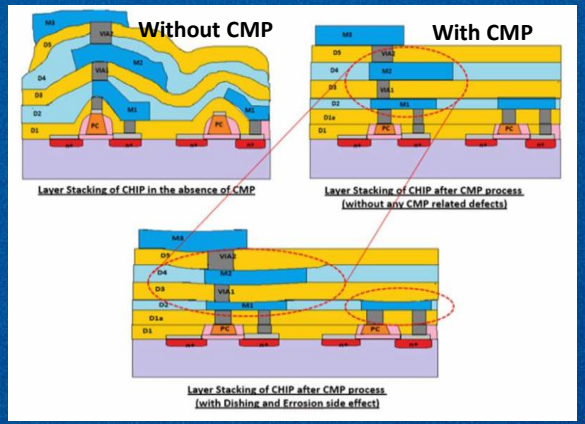
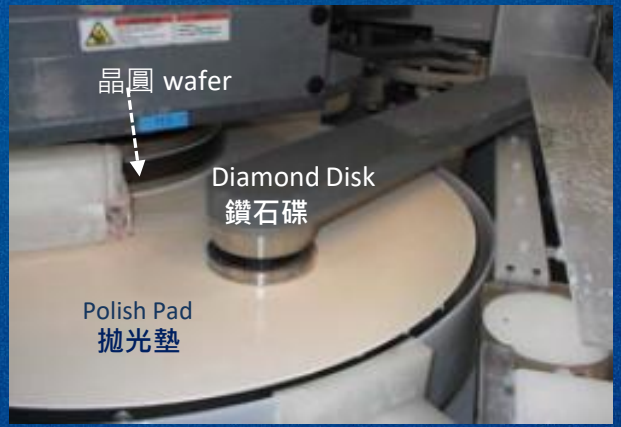
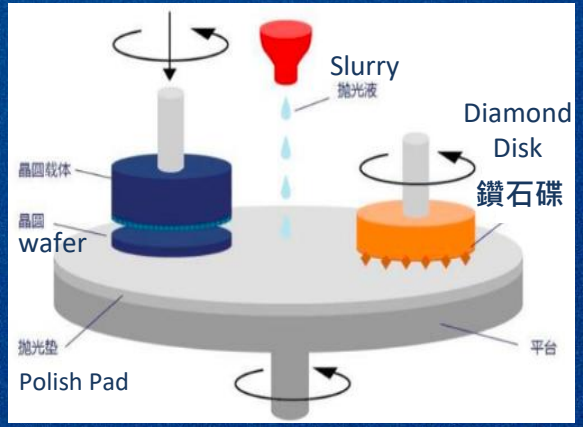
CMP鑽石碟 Diamond Disk

CMP (Chemical Mechanical Polish) 化學機械拋光，主要用於先進IC製程中，透過拋光墊與拋光液同時透過機械與化學反應加工晶圓表面，達到表面晶圓材料的移除及整體的平坦化，才能接續後續製程以及提高良率，進而能循摩爾定律持續微縮IC線寬面積，推展出N5/N3/N2先進製程。而**鑽石碟**的功用就是在拋光晶圓的同時去加工拋光墊，以移除拋光時的副產物及穩定拋光速率並提升良率及延長拋光墊使用壽命，是先進IC拋光製程中提升良率及控制成本中非常重要的一環。

CMP (Chemical Mechanical Polish) is widely used for advanced IC manufacturing processes for surface material removal, smoothing surfaces, and planarization by the polish pad (mechanical) and the abrasive slurry (chemical reaction). And the **diamond disk (aka pad conditioner)**'s function is to in-situ dress the polish pad during the process to remove the polish byproduct, to maintain a stable pad roughness and remove rate, to improve yield, and to prolong the lifetime of the pad.







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CMP鑽石碟 Diamond Disk

中砂鑽石碟用於半導體化學機械研磨製程中修整研磨墊以達到理想移除率及平坦度。

KINIK diamond disk is used on semi-conductor CMP process in order to make the pad reach the desirable removal rate and uniformity.

Conventional Disk



DiaGrid®



I-DiaGrid®



S-DiaGrid®

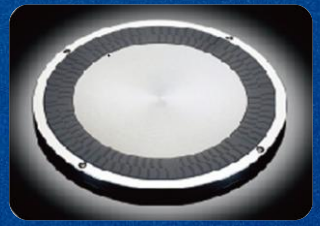
Advanced Disk：High Performance / Long Life Time



Pyradia®



EDP Disk
(Metal Free)



CVD -WAVE



equaDia

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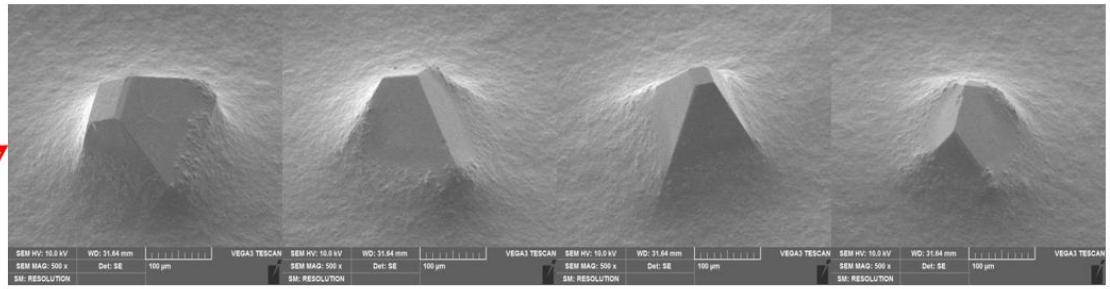
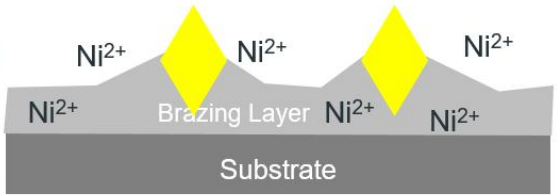
EDP Disk for Metal Free Solution

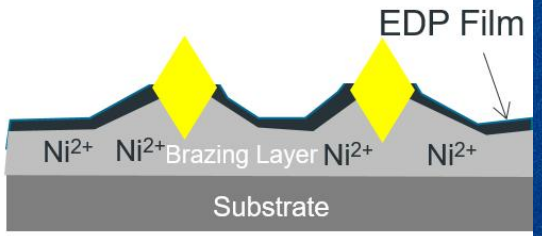
- Diamond disk protected with EDP film for metal-free requested in advanced IC technologies.











- EDP Film is Epoxy. It is acid and alkali resistant, and effectively prevent from precipitation of metal ions during the manufacturing process.
- Both sides of a disk can be coated for better protection.

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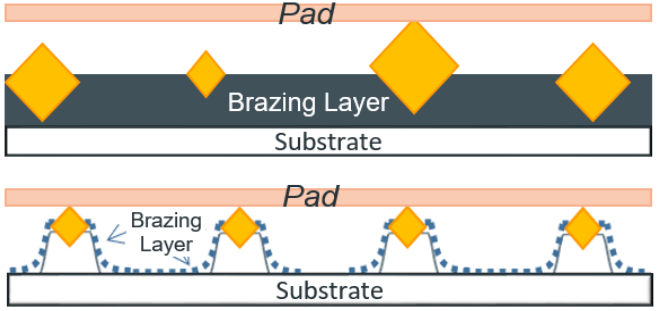
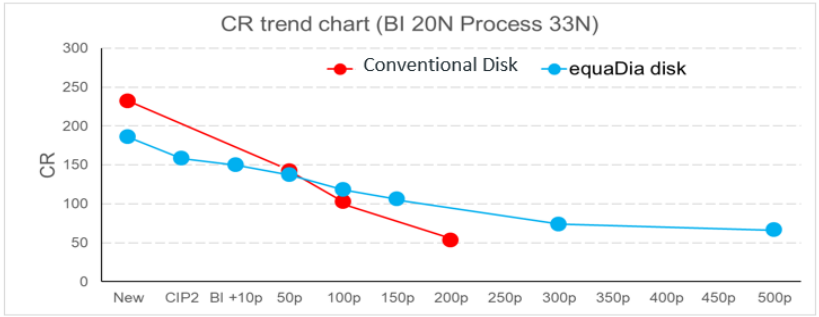
equaDia Disk® 鑽石碟

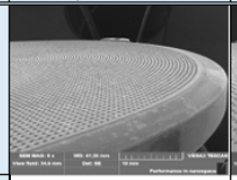
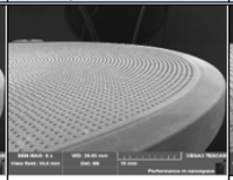
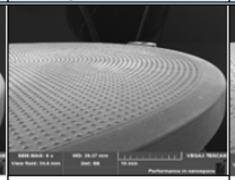
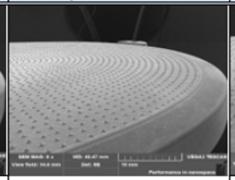
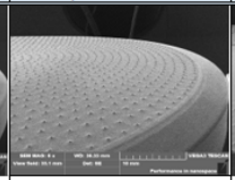
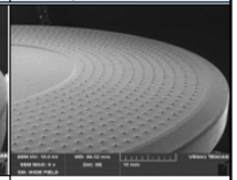
- Advanced disk “equaDia” for excellence tip height leveling and longer lifetime.





➢ Conventional Disk dressed a pad with the high points of the diamond. equaDia disk has good diamond leveling, and each diamond works. CR decay of equaDia disk is much slower.

CR decay rate	100p	200p	300p	500p
Conventional Disk	56%	77%	-	-
equaDia disk	25%	-	54%	58%

	equaDia P800	equaDia P1000	equaDia P1200	equaDia P1500	equaDia P2000	equaDia P2000
SEM						
Appearance	Full face	Full face	Full face	Full face	Full face	Donut type
Diamond Size (μm)	100	100	100	100	170	170
Diamond pitch (μm)	800	1000	1200	1500	2000	2000
Diamond Bonded (%)	55%	53%	56%	51%	53%	55%
Leveling (μm)	6.9	7.2	7.6	6.7	9.7	9.9
total diamond count (ea)	11600	7450	5200	3350	1900	1400

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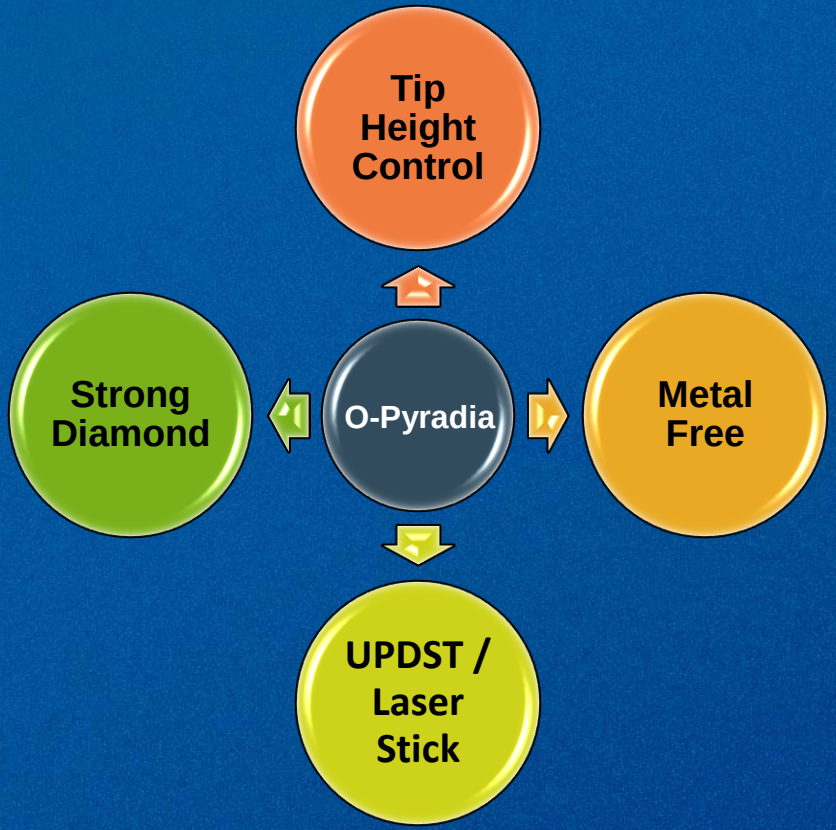
Metal-free O-Pyradia® 鑽石碟

- O-Pyradia CMP pad conditioner for advanced customer's tightened metal contamination control.



Pyradia Type	O-Pyradia	Pyradia
Photo		
Material of Substrate	Polymer	Metal
Bonding Material	Polymer	LM(Ni ; Cr powder)
Bonding Strength	+	++
Process Temp	<100 degree	~1000 degree
Diamond Strength	++	+
Acid and alkali resistant	Metal Free	Ni ; Cr

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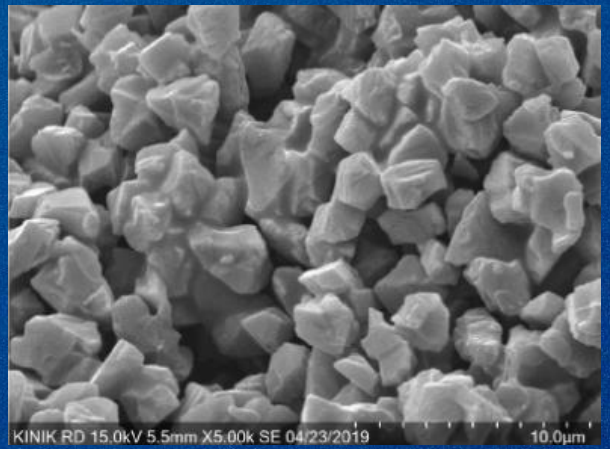
Semiconductor Grinding Wheel

- The Wafer grinding wheels are used in the in-feed grinding process of semiconductor wafers such as Si, SiC, and advanced 2.5D/3D package (Cu/compound…etc.). The in-feed grinding process consists of rough and fine grinding processes. Wafer grinding wheels are made of diamond abrasives and customized vitrified or resin bond in a unique porous microstructure. The diamond size for rough and finish grinding processes are #325～#1000 and #2000～#8000 respectively. The features of these wafer grinding wheels are stable high removal rate, long lifetime and lower grinding resistance.



Wafer Grinding Wheels



Porous microstructure

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Diamond Roller

- The diamond rollers are used to sophisticatedly dress the complex and high precision form of grinding wheels (e.g. Al2O3, SiC, cBN wheels) for automatic shaping high volume production of high precision transmission components such as ball screws, guides, bearings, gears, tools, automotive and aerospace parts etc..
- Diamond rollers are mainly made by reverse-plated or infiltration methods using natural, synthetic diamond grits or CVD diamond either randomly or regularly distributed. The features of the diamond rollers are high profile accuracy and high dressing efficiency. We can supply proper diamond rollers for grinders in various applications in accordance with customers need.



Diamond roller for dressing profile grinding wheel of ball screw

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Tools for Semiconductor &photoelectric

中砂以最新電鑄、成型與燒結技術製造成的精密鑽石切割刀。搭配特殊的金屬與樹脂等結合劑，使切割軟刀具備高剛性、低磨耗且具備良好的自銳性；適合在各類精密陶瓷、硬脆材料、磁性材料，光學玻璃，印刷電路板與半導體封裝材料的切割應用。

KINIK Company announces the introduction of Super Hubless Dicing Blade with resin, metal and nickel matrices. The dicing blades are manufactured by specialty consolidation, sintering and electro-forming process that improve the uniformity of the thin blades. They are suitable for cutting ceramics, brittle materials , optical glass, printed circuit boards, especially for semiconductor packaging.



鑽石切割軟刀 Dicing Blade



磨刀板 Dressing Board

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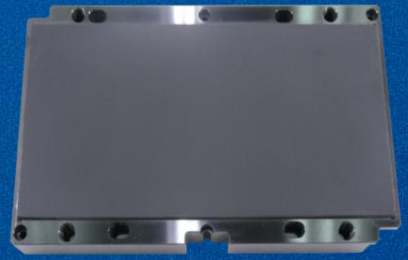
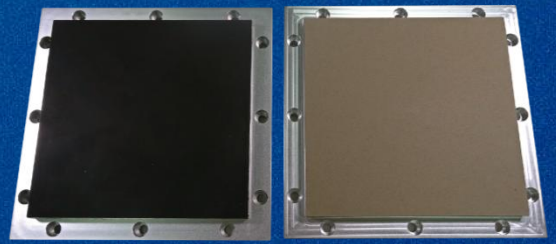
多孔質陶瓷真空吸盤

Porous Ceramic Chuck Table



多孔質陶瓷孔洞均勻微細、不發塵、可具靜電消散特性，應用於真空吸盤具備吸力均勻、局部吸附性、不產生印痕、工作效率及精度高等優點，可充分應用於半導體研磨、清洗、切割及檢測等設備。



– High-performance, High-precision, Uniform suction force.
– Partial chucking without sagging.
– Chucking and transport of wafer without leaving suction marks.
– Produces no static electricity and dust.

Application：
Wafer grinder, cleaning/dicing machine and measuring equipment, etc.

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金屬精密加工刀具

Ultra Precision Machining Tools

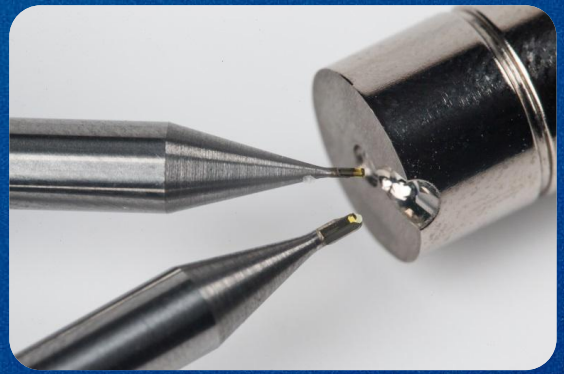
中砂提供電子業、PCB板、木工業及金屬加工業所需的單晶（SCD）、聚晶鑽（PCD）、立方氮化硼（PcBN）等鑽石刀具已逾20年。

近年積極投入生產高精度、更微小之SCD、PCD 及 PcBN產品供光學業、精密模具等加工技術使用，如：單晶鑽石車刀與銑刀、PcBN微小徑銑刀等。

KINIK company already has more than 20-year experience in providing all kinds of diamond tools for the applications of PCB, woodworking and metal working industries.

Recently, KINIK also developed several kinds of SCD, PCD and PcBN precision micro tools to meet high-end market's requirements.





加工面達到極高的光潔度表現。
High finish at processing parts.

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傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel

中砂提供各式平面、內外圓、無心及雙平面等工件研磨及切斷用的傳統、BD及電鑄砂輪。

主要產業應用包含精密機械業的滑軌及齒輪研磨與砂輪成形修整用的鑽石滾輪、鋼鐵業的輥筒研磨、工具製造業的高速鋼鑽頭、CNC及PCD/PcBN刀具等研磨、半導體業的晶圓減薄及倒角研磨、高效率硬脆材料如SiC研磨用的蜂巢砂輪、光學模具模仁拋光等。

KINIK provides various grinding wheels for surface, internal & cylindrical, centerless and disc surface grinding and cutting of workpiece production. The main industrial applications include linear guideway, gear grinding and diamond roller for dressing wheel in precision machinery, steel roll grinding, HSS drill, CNC & PCD/PcBN tool grinding, wafer thinning and edge grinding in semiconductor, honeycomb wheel for high-efficient grinding of hard and brittle materials such as SiC, optical mold polishing etc.

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傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel



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傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel



光學模仁拋光
Optical Mold Polishing



內圓研磨
Internal Grinding



CNC刀具研磨
CNC Tools Grinding



蜂巢砂輪
Diamond & CBN Honey Comb Wheel



PCD刀具研磨
PCD Cutting Tools Grinding

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傳統砂輪及鑽石/CBN砂輪

Traditional Grinding Wheel & Diamond / CBN Grinding Wheel



電鑄砂輪
Electroplated Diamond & CBN Wheels and Products



各式切斷及可彎曲、碟式砂輪
Cut-off, Depressed & Flexible Wheels, and Flap Disc



鑽石滾輪
Diamond Roller



砂輪動平衡校正儀
Grinder Balancer

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KINIK COMPANY
中砂公司 TWSE STOCK CODE 1560

廠區 Plant Information

- Manufacturing Plants: Taiwan x5; Thailand x2. Japan x1
- Grind Wheel: ABU(Yingge), Hongia(Hsinchu), KTC Thailand, MGT Thailand, MKS Japan
- Diamond Disk: DBU (Yingge & Shulin, Taiwan))
- Reclaim Wafer: SBU (Zhubei & Zhunan, Taiwan)



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廠區 Plant Information



總 公 司 Head Office
鶯歌廠區 Yingge Factory
239010 新北市鶯歌區中山路64號
No.64, Zhongshan Rd., Yingge Dist.,
New Taipei City 239010, Taiwan
TEL:+886 2 2679-1931~40

Grinding Wheel & Diamond Disk





樹林廠區 Shulin Factory
238010 新北市樹林區中山路2段151巷16號
No.16, Ln. 151, Sec. 2, Zhongshan Rd.,
Shulin Dist., New Taipei City 238010, Taiwan
TEL:+886 2 8684-4111~13

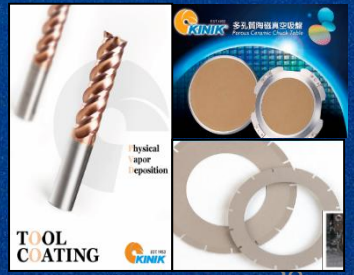
Diamond Disk
Diamond Cutting & Dicing Tools





新竹廠區 Hsinchu Factory
303035 新竹縣湖口鄉新竹工業區文化路6號
No.6, Wenhua Rd., Hukou, Hsinchu Ind.
Park, Hsinchu County 303035, Taiwan
TEL:+886 3 598-4990

Diamond Dicing Tools. PVD Coating
Ceramic Vacuum Chuck



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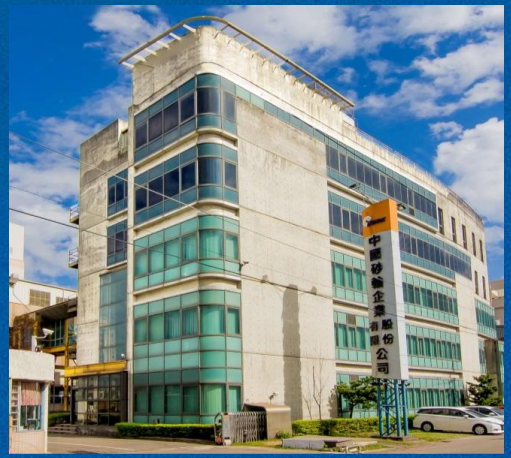
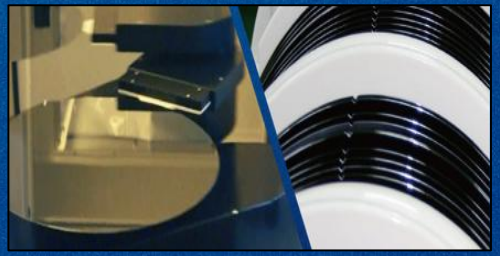
廠區 Plant Information



竹北廠區 Zhubei Factory
302059 新竹縣竹北市十興路260號
No.260, Shixing Rd., Zhubei City, Hsinchu County 302059, Taiwan
TEL:+886 3 550-7160~5



竹科廠區 Hsinchu Science Park Factory
350401 苗栗縣竹南鎮科北五路6號
No. 6, Kebei 5th Rd., Jhunan Township, Miaoli County 350401, Taiwan
TEL:+886 3 550-7160



Reclaim & Test Wafer
再生晶圓 & 測試晶圓

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廠區 Plant Information

SINCE 1978 HONGIA® 鴻記工業股份有限公司
HONGIA INDUSTRY CO., LTD.

鴻記工業股份有限公司
Hongia Industry Co, Ltd.

239008 新北市鶯歌區余厝巷2號
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New Taipei City 239008, Taiwan
TEL:+886 2 2679-1006
Email : hongia-sale@kinik.com.tw
www.hongia.com.tw



Electroplated Diamond Wheel 電鑄砂輪



金力泰國有限公司
Kinik - Thai Co., Ltd.

225 Moo 7 , Khok Pip, Simahosot,
Prachinburi 25190 Thailand
TEL:+663 727 6954
Email : sales@kinikthai.co.th
www.kinikthai.co.th



Resin and Ceramic Wheel 樹脂砂輪&陶瓷砂輪

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Acquired MKS (Japan) & MGT (Thailand) as subsidiaries on April 2025

中砂KINIK 集團創業72周年慶 歡喜迎接新紀元

中砂 KINIK

日本MKS 及 泰國MGT 公司正式加入，開創全球發展新篇章

中砂報報

活動日期：2025/04/01
出刊日期：2025/04/01

2025年4月1日，是中砂KINIK集團歡慶創業72周年的日子，同時也是集團迎來重要的里程碑—原在日本三井金屬鑛業集團旗下的日本MKS 公司和泰國的 MGT 公司 正式加入KINIK集團邁向全球化發展的新階段。
今天舉辦的正式收購交割及更名揭牌儀式標誌著 KINIK 集團在精密研磨與半導體材料研磨領域的全球擴張，並開啟了集團進一步提升技術創新和市場競爭力的嶄新篇章。

MKS、MGT 新名創新局

自2025年4月1日起，MKS 公司正式更名為 マックスキニック精密株式会社 (英文名稱:Max Kinik Seimitsu Co., Ltd.)，MGT公司更名為 Max Kinik Grinding Technology Co., Ltd.。
此次更名由 KINIK 集團股東提出，新名稱中的 "Max" 代表規模最大化，"Kinik" 承載著 KINIK 集團在研磨領域的專業精神，象徵著公司將專注於最大化其潛力及市場影響力。而 "Seimitsu"及 "Grinding Technology" 則代表對精密加工技術的極致追求。MKS暨MGT社長坂井正博表示：「今天是我們公司歷史中的一個重要時刻，作為 KINIK 集團的一員，我們將繼承百年來積累的技術實力與市場聲譽，並結合 KINIK 集團的全球資源，共同創造更多的發展機會。」

強化全球市場競爭力

此次MKS 和 MGT加入KINIK集團， 不僅是KINIK集團對這兩家公司的肯定，更是集團邁向全球市場的重要步伐。
KINIK集團林伯全董事長表示：「今天，MKS和MGT正式成為 KINIK 集團的一員，這不僅是KINIK集團對兩家公司過去努力的肯定，更是大家一起面對未來挑戰的新起點。我們將繼續傳承三井研削的卓越技術，並結合 KINIK 集團的資源，推動全球市場的拓展，不斷創新、挑戰行業的更高標準。」

跨越百年，凝聚力量創新發展，攜手磨出共好大未來

KINIK 集團謝榮哲執行長在致詞中指出：「砂輪產品雖然看似不起眼，但其在汽車、航空、機械加工及半導體等關鍵領域扮演著至關重要的角色。隨著 MKS和MGT的加入，KINIK集團在台灣、泰國、日本設有生產基地、在該三國及中國大陸設有營業單位，產品行銷全球五十多個國家，集團內公司將發揮彼此的技術優勢，提升品牌影響力，開創新的成長契機。」
謝執行長表示：「新公司名稱的揭牌象徵著新時代的開始。我們希望在擁有百年歷史的『MKS』優秀傳統基礎上，與各位共同發揮相互的優勢，建立互信關係，攜手邁向更美好的未來。今後，我們一起努力磨出共好大未來。」

共好：你好、我好、大家好！讓我們攜手磨出共好大未來！





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榮耀記事 Milestone



2021年11月榮獲行政院「第26屆國家品質獎 全面卓越類 - 績優經營獎」。

Nov. 2021, Honored with "BUSINESS MERIT AWARD of Total BUSINESS EXCELLENCE" at the 26th NATIONAL QUALITY AWARD from the Executive Yuan, R.O.C.

https://nqa.cpc.tw/NQA/Web/Awards26th_Content.aspx?p=f2b6e812-92aa-49c3-8149-1e005a0fe706

賀!中國砂輪公司榮獲「第26屆國家品質獎」



經濟部 林全能次長(左)、中國砂輪公司 林伯全董事長(右)。圖/經濟部工業局提供。

中國砂輪公司 榮獲「第26屆國家品質獎」，林伯全董事長受邀晉見總統



中國砂輪公司董事長 林伯全(右)、總統 蔡英文(左)。圖／總統府提供

榮耀記事 Milestone



2021年10月榮獲經濟部「2022年第30屆台灣精品獎 - 12吋再生晶圓」。

Oct. 2021, Honored with "Taiwan Excellence Award - 12" Reclaimed Wafers" from the MOEA, R.O.C.

https://www.taiwanexcellence.org/tw/award/product/1110433

台灣精品 2022



TAIWAN EXCELLENCE

得獎產品：12 inches Reclaim Wafer

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榮耀記事 Milestone



榮獲經濟部第四屆卓越中堅企業獎
Honored with 4th Taiwan mittelstand Award from the MOEA, R.O.C, in 2017.



榮獲經濟部2013年 第14屆
工業精銳獎 機械、運輸工業類
Honored with 14th Industrial Sustainable Excellence Award from the MOEA, R.O.C, in 2013.

TOP 100
TAIWAN BRANDS

榮獲經濟部台灣百大品牌獎
Honored with the Top 100 Taiwan Brands Award from the MOEA, R.O.C, in 2011.

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榮耀記事 Milestone



榮獲經濟部2006年台灣優良品牌獎
Honored with the Taiwan Superior Brand Award from the MOEA, R.O.C, in 2006.



榮獲第十屆經濟部產業科技發展傑出獎
Award of Excellence, the 10th R.O.C. MOEA Industrial Technology Advancement Award in 2002.



全國第一家砂輪公司榮獲國家傑出精品獎
The first grinding wheel plant won Excellent Product Award in 1993.

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